

Version with markings to show changes made

IN THE SPECIFICATION

This application is a divisional of U.S. Patent Application Serial No. 09/410,863, filed October 1, 1999, now pending, which claims the benefit of U.S. Provisional Application Ser. No. 60/152,261, filed September 2, 1999.

[This application claims the benefit of U.S. Provisional Application Serial No. 60/152,261 entitled ARRAYS WITH MASK LAYERS AND METHODS OF MANUFACTURING SAME filed September 2, 1999.]

IN THE CLAIMS

32. (Amended) An article for use in manufacturing an array, the article comprising:
a polymeric substrate comprising a relaxed oriented film or a relaxed elastomeric material, the substrate having a surface; and

a mask layer on said surface, the mask layer comprising ink and linking agents [on the article, wherein the mask layer has] and having a projected surface area and a topographical surface area [that] wherein the topographical surface area is greater than the projected surface area.

39. (Amended) The article of claim [32] 38 wherein the heat shrink film comprises [substrate is derived from starting material selected from the group consisting of] biaxially oriented low density polyethylene, biaxially oriented linear low density polyethylene, [a] biaxially oriented ultra low density polyethylene, [and] or biaxially oriented ethylene vinyl acetate.